2025 International Workshop on Advanced Interconnects

www.wai-emc.com Nov 5-7, 2025 Ningbo, China

Call for Paper

Welcome to WAI 2025! This is the second **International Workshop on Advanced Interconnects (WAI)** to be held in Ningbo, China, **Nov. 5 to 7, 2025.** The workshop will specially address the latest development and innovations on signal integrity (SI)/power integrity (PI) and electromagnetic interference (EMI) of advanced interconnects, including integrated circuits, IC packages, PCB, and cable connector etc.， and will serve as a broad exchange platform for both academia and industry.

You are warmly invited to submit a paper on your latest research results. Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements.

Technical Topics

The topics include but not limited to the following technical areas:

- **Interconnects:** High-speed interconnect design and optimization, Interconnect modeling and extraction
- **Simulation and Modeling Techniques for SI/PI/EMI**
- **Multiphysics Modeling**
- **Power Delivery Network and Decoupling**
- **Radio Frequency Interference Problems;**
- **SI/PI/EMI at Chip/Package/ System Level**
- **SI/PI/EMI for Chiplets**
- **SI/PI/EMI Co-design**
- **Artificial Intelligence-assisted EMC/SI/PI Related Methodologies**
- **Tools and Methodologies:** Jitter/Noise/Crosstalk/BER budgeting, analysis, and measurement
- **Others: Radio Frequency, Antenna, etc**

Instructions of submissions

Abstract paper is limited to 1 page, and full paper is limited to 2-3 pages. Both Abstract papers and full papers must follow IEEE conference paper templates, and can be submitted through http://wai-emc.com/wai2025/submission

Special session or workshop/tutorial: Please send your proposal directly to conference@detooltech.com

Authors of high-quality abstracts paper or full papers will be invited to submit the extended papers to the IEEE Transactions on Signal and Power Integrity!

Important Dates

Full paper submission date	**Sep. 30, 2025**
Abstract paper submission date	**Sep. 30, 2025**
Notification of full paper acceptance	**Oct. 15, 2025**
Notification of abstract paper acceptance	**Oct. 15, 2025**
Final paper submission date	**Oct. 20, 2025**

Information: If you need invitation letter for visa application, please contact conference@detooltech.com

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